

FDD3706/FDU3706

20V N-Channel PowerTrench® MOSFET

General Description

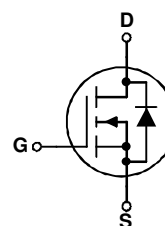
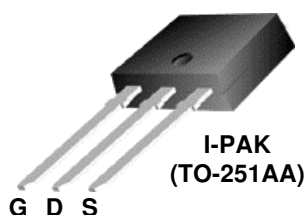
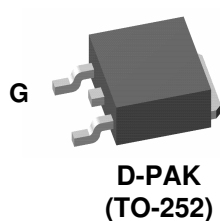
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $R_{DS(ON)}$, fast switching speed and extremely low $R_{DS(ON)}$ in a small package.

Applications

- DC/DC converter
- Motor Drives

Features

- 50 A, 20 V $R_{DS(ON)} = 9\text{ m}\Omega @ V_{GS} = 10\text{ V}$
 $R_{DS(ON)} = 11\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
 $R_{DS(ON)} = 16\text{ m}\Omega @ V_{GS} = 2.5\text{ V}$
- Low gate charge (16 nC)
- Fast Switching
- High performance trench technology for extremely low $R_{DS(ON)}$



Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$ (Note 3)	50	A
	@ $T_A = 25^\circ\text{C}$ (Note 1a)	14.7	
	Pulsed (Note 1a)	60	
P_D	Power Dissipation @ $T_C = 25^\circ\text{C}$ (Note 3)	44	W
	@ $T_A = 25^\circ\text{C}$ (Note 1a)	3.8	
	@ $T_A = 25^\circ\text{C}$ (Note 1b)	1.6	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	3.4	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	45	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1b)	96	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape width	Quantity
FDD3706	FDD3706	D-PAK (TO-252)	13"	12mm	2500 units
FDU3706	FDU3706	I-PAK (TO-251)	Tube	N/A	75

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Drain-Source Avalanche Ratings (Note 2)

E_{AS}	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 10\text{V}$, $I_D = 7\text{A}$			60	mJ
I_{AS}	Drain-Source Avalanche Current				7	A

Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$, $I_D = 250\text{ }\mu\text{A}$	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C		13		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 16\text{V}$, $V_{GS} = 0\text{V}$			1	μA
I_{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 12\text{V}$, $V_{DS} = 0\text{V}$			100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -12\text{V}$, $V_{DS} = 0\text{V}$			-100	nA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	0.5	1	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C		-3.5		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{V}$, $I_D = 16.2\text{A}$ $V_{GS} = 4.5\text{V}$, $I_D = 14.7\text{A}$ $V_{GS} = 2.5\text{V}$, $I_D = 12.2\text{A}$ $V_{GS} = 4.5\text{V}$, $I_D = 14.7\text{A}$, $T_J = 125^\circ\text{C}$		7.5 8 11 12.6	9 11 16 19	m Ω
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 4.5\text{V}$, $V_{DS} = 5\text{V}$	30			A
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{V}$, $I_D = 14.7\text{A}$		65		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 10\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$		1882		pF
C_{oss}	Output Capacitance			430		pF
C_{rss}	Reverse Transfer Capacitance			201		pF

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 10\text{V}$, $I_D = 1\text{A}$, $V_{GS} = 4.5\text{V}$, $R_{GEN} = 6\text{ }\Omega$		11	20	ns
t_r	Turn-On Rise Time			15	27	ns
$t_{d(off)}$	Turn-Off Delay Time			35	56	ns
t_f	Turn-Off Fall Time			16	29	ns
Q_g	Total Gate Charge	$V_{DS} = 10\text{V}$, $I_D = 14.7\text{A}$, $V_{GS} = 4.5\text{V}$		16	23	nC
Q_{gs}	Gate-Source Charge			3.7		nC
Q_{gd}	Gate-Drain Charge			4		nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain–Source Diode Forward Current				3.2	A
V _{SD}	Drain–Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 3.2 A (Note 2)		0.7	1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) $R_{\theta JA} = 40^\circ\text{C/W}$ when mounted on a
1 in² pad of 2 oz copper



b) $R_{\theta JA} = 96^\circ\text{C/W}$ when mounted
on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

3. Maximum current is calculated as:
- $$\sqrt{\frac{P_D}{R_{DS(on)}}}$$

where P_D is maximum power dissipation at $T_C = 25^\circ\text{C}$ and $R_{DS(on)}$ is at $T_{J(max)}$ and $V_{GS} = 10\text{V}$. Package current limitation is 21A

Typical Characteristics

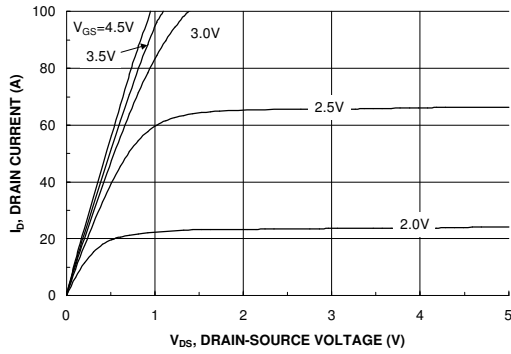


Figure 1. On-Region Characteristics

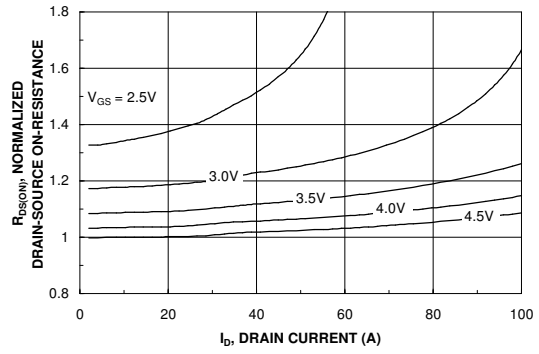


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

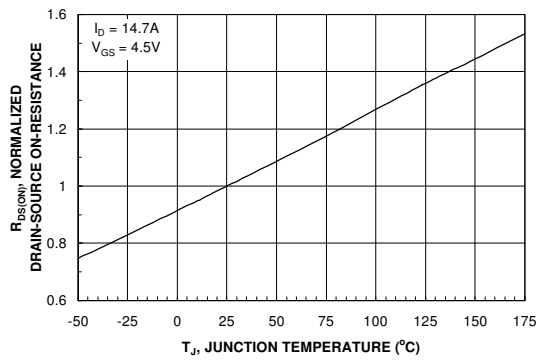


Figure 3. On-Resistance Variation with Temperature

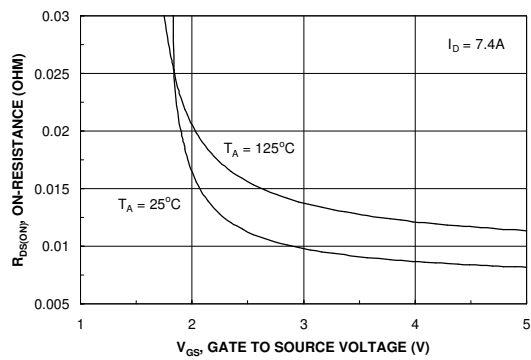


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

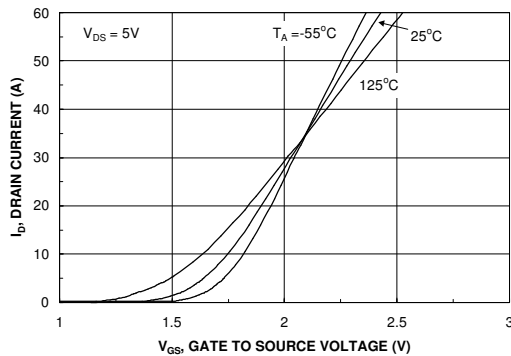


Figure 5. Transfer Characteristics

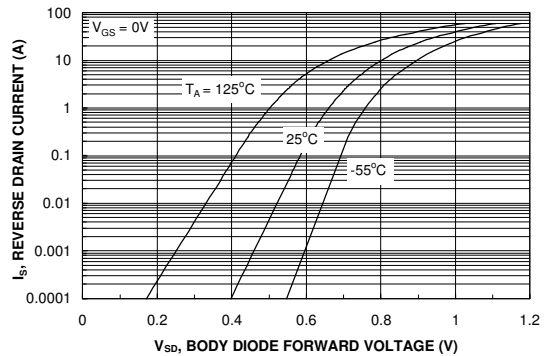


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics

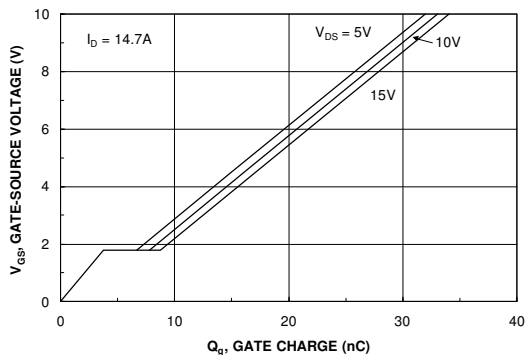


Figure 7. Gate Charge Characteristics

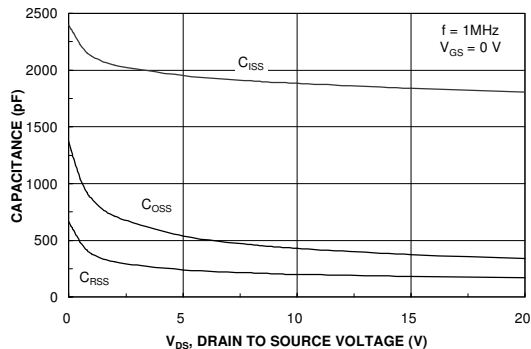


Figure 8. Capacitance Characteristics

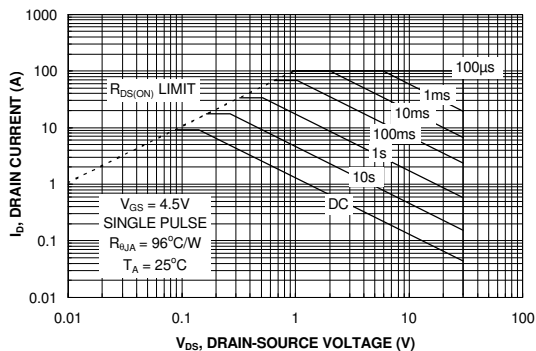


Figure 9. Maximum Safe Operating Area

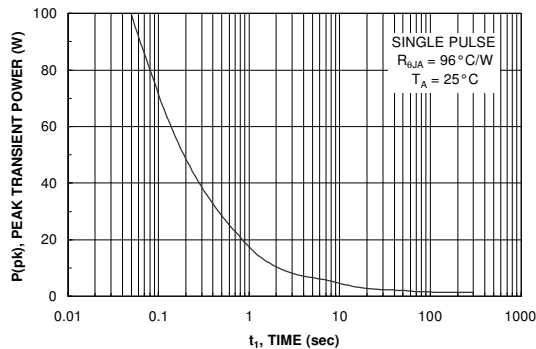


Figure 10. Single Pulse Maximum Power Dissipation

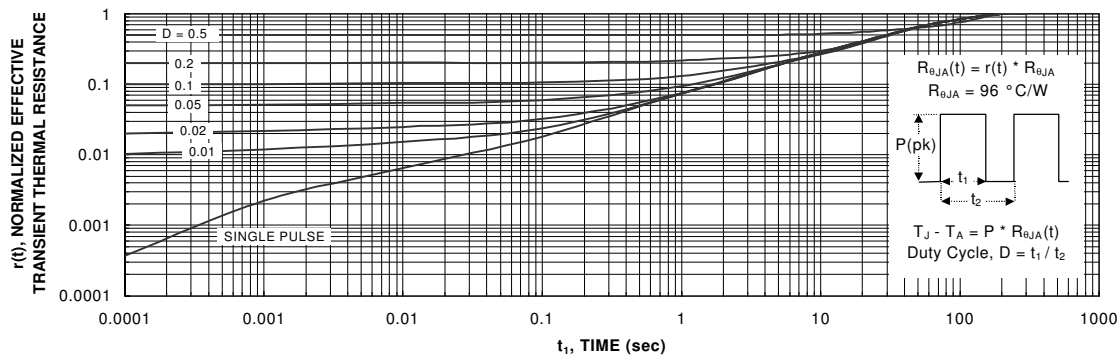


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.

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